







## **TSMC - Bar Ilan University** Technology Innovation Forum

Wednesday, November 6th 2019

## **Program**

08:30 - 09:30	Welcome & Registration		
09:30 - 10:00	Keynote: EnICS Impact Center: Enabling Innovation in Semiconductors	Bar-llan University	<b>Prof. Alex Fish</b> Professor Bar-Ilan University
10:00 - 10:30	Keynote: Unleashing Israeli Innovation in AI and Automotive Applications	tsine	Maria Marced President, TSMC EMEA
10:30 – 11:00	Keynote: : TSMC and Its Ecosystem for Innovation	tsinc	<b>John Chin</b> VP TSMC EMEA
11:00 - 11:30	Coffee Break		
11:30 – 11:50	Developing Al-based Solutions for Chip Design	SYNOPSYS°	Maria-Cristina Borelli Director, Product Solutions Sales
11:50 – 12:10	Process Selection Considerations for Ultra Low Power Design	DSP <sub>GROUP</sub>	<b>Shlomi Shavit</b> Physical Design Engineer
12:10 – 12:30	Sensor Fusion and ADAS SOC designs in TSMC 16FFC and N7	cādence	<b>Ronen Laviv</b> Director - IP Sales Israel
12:30 - 13:30	Lunch - Networking		
13:30 - 13:50	Chiplets Solutions using COWOS and InFO with 112 Gbps Serdes and HBM2E/3.2Gbps for AI, HPC and networking		<b>Igor Elkanovich</b> System CTO
13:50 – 14:10	Designing a Top Performing AI Processor for Edge Devices in TSMC 16nm FinFET	HAILO	<b>Guy Kaminitz</b> VP VLSI Design
14:10 – 14:30	Challenges posed by dynamic Uncertainty on Al ML Devices targeting 16nm, 7nm, and 5nm	and oortec	Stephen Crosher CEO, Moortec Semiconductor
14:30 – 15:00	Coffee Break		
15:00 - 15:20	Best Practices for ARM Cortex CPU energy efficient implementation flows	arm	<b>Lisa Minwell</b> Senior IP Solutions Mgr
15:20 - 15:40	RF energy harvesting and ultra-Low power Bluetooth of for digital identity and sensing in TSMC 40nm Process	device <b>Wiliot</b>	<b>Yaron Elboim</b> VP R&D
15:40 – 16:00	Simplify Energy Efficient Designs with Cost-effective SOC Platform	D I L P H I N DESIGN	<b>Pierre Gazull</b> Product Marketing Mgr
16:00	Wrap Up	tsine	<b>John Chin</b> VP TSMC EMEA